

## 3.3-V CAN TRANSCEIVER

Check for Samples: [SN65HVD233-HT](#)

### FEATURES

- Bus-Pin Fault Protection Exceeds  $\pm 36$  V
- Bus-Pin ESD Protection Exceeds 16-kV Human Body Model (HBM)
- Compatible With ISO 11898
- Signaling Rates<sup>(1)</sup> up to 1 Mbps
- Extended –7-V to 12-V Common-Mode Range
- High-Input Impedance Allows for 120 Nodes
- LVTTTL I/Os Are 5-V Tolerant
- Adjustable Driver Transition Times for Improved Signal Quality
- Unpowered Node Does Not Disturb the Bus
- Low-Current Standby Mode . . . 200  $\mu$ A Typical
- Power-Up/Down Glitch-Free Bus Inputs and Outputs
  - High Input Impedance With Low  $V_{CC}$
  - Monolithic Output During Power Cycling
- Loopback for Diagnostic Functions Available
- DeviceNet™ Vendor ID #806

<sup>(1)</sup> The signaling rate of a line is the number of voltage transitions that are made per second expressed in the units bps (bits per second).

### APPLICATIONS

- Down-Hole Drilling
- High Temperature Environments
- Industrial Automation
  - DeviceNet™ Data Buses
  - Smart Distributed Systems (SDS™)
- SAE J1939 Data Bus Interface
- NMEA 2000 Data Bus Interface
- ISO 11783 Data Bus Interface
- CAN Data Bus Interface

### SUPPORTS EXTREME TEMPERATURE APPLICATIONS

- Controlled Baseline
- One Assembly/Test Site
- One Fabrication Site
- Available in Extreme (–55°C/210°C) Temperature Range <sup>(1)</sup>
- Extended Product Life Cycle
- Extended Product-Change Notification
- Product Traceability
- Texas Instruments high temperature products utilize highly optimized silicon (die) solutions with design and process enhancements to maximize performance over extended temperatures.

### DESCRIPTION/ORDERING INFORMATION

The SN65HVD233 is used in applications employing the controller area network (CAN) serial communication physical layer in accordance with the ISO 11898 standard, with the exception that the thermal shutdown is removed. As a CAN transceiver, the device provides transmit and receive capability between the differential CAN bus and a CAN controller, with signaling rates up to 1 Mbps.

Designed for operation in especially harsh environments, the device features cross wire, overvoltage, and loss-of-ground protection to  $\pm 36$  V, with common-mode transient protection of  $\pm 100$  V. This device operates over a –7-V to 12-V common-mode range with a maximum of 60 nodes on a bus.

If the common-mode range is restricted to the ISO 11898 standard range of –2 V to 7 V, up to 120 nodes may be connected on a bus. This transceiver interfaces the single-ended CAN controller with the differential CAN bus found in industrial, building automation, and automotive applications.

<sup>(1)</sup> Custom temperature ranges available



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## DESCRIPTION/ORDERING INFORMATION (CONTINUED)

$R_S$  (pin 8) provides for three modes of operation: high-speed, slope control, or low-power standby mode. The high-speed mode of operation is selected by connecting  $R_S$  directly to ground, allowing the driver output transistors to switch on and off as fast as possible with no limitation on the rise and fall slope. The rise and fall slope can be adjusted by connecting a resistor to ground at  $R_S$ , since the slope is proportional to the pin's output current. Slope control is implemented with a resistor value of 10 k $\Omega$  to achieve a slew rate of  $\approx 15$  V/ $\mu$ s, and a value of 100 k $\Omega$  to achieve  $\approx 2.0$  V/ $\mu$ s slew rate. For more information about slope control, refer to the application information section.

The SN65HVD233 enters a low-current standby mode, during which the driver is switched off and the receiver remains active if a high logic level is applied to  $R_S$ . The local protocol controller reverses this low-current standby mode when it needs to transmit to the bus.

A logic high on the loopback (LBK, pin 5) of the SN65HVD233 places the bus output and bus input in a high-impedance state. The remaining circuit remains active and available for the driver to receiver loopback, self-diagnostic node functions without disturbing the bus.

### AVAILABLE OPTIONS

| PART NUMBER     | LOW-POWER MODE            | SLOPE CONTROL | DIAGNOSTIC LOOPBACK | AUTOBAUD LOOPBACK |
|-----------------|---------------------------|---------------|---------------------|-------------------|
| SN65HVD233HD    | 200- $\mu$ A standby mode | Adjustable    | Yes                 | No                |
| SN65HVD233SJD   | 200- $\mu$ A standby mode | Adjustable    | Yes                 | No                |
| SN65HVD233SKGDA | 200- $\mu$ A standby mode | Adjustable    | Yes                 | No                |
| SN65HVD233SHKJ  | 200- $\mu$ A standby mode | Adjustable    | Yes                 | No                |
| SN65HVD233SHKQ  | 200- $\mu$ A standby mode | Adjustable    | Yes                 | No                |

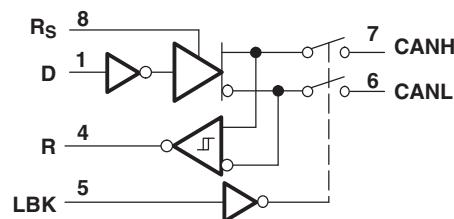
### ORDERING INFORMATION<sup>(1)</sup>

| $T_A$          | PACKAGE <sup>(2)</sup> | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|------------------------|-----------------------|------------------|
| -55°C to 175°C | D                      | SN65HVD233HD          | 233S             |
| -55°C to 210°C | KGD                    | SN65HVD233SKGDA       | N/A              |
|                | HKJ                    | SN65HVD233SHKJ        | SN65HVD233SHKJ   |
|                | HKQ                    | SN65HVD233SHKQ        | HVD233SHKQ       |
|                | JD                     | SN65HVD233SJD         | SN65HVD233SJD    |

(1) For the most current packaging and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).

(2) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).

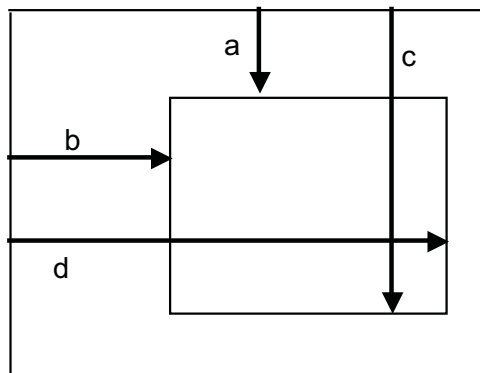
### FUNCTIONAL BLOCK DIAGRAM



## BARE DIE INFORMATION

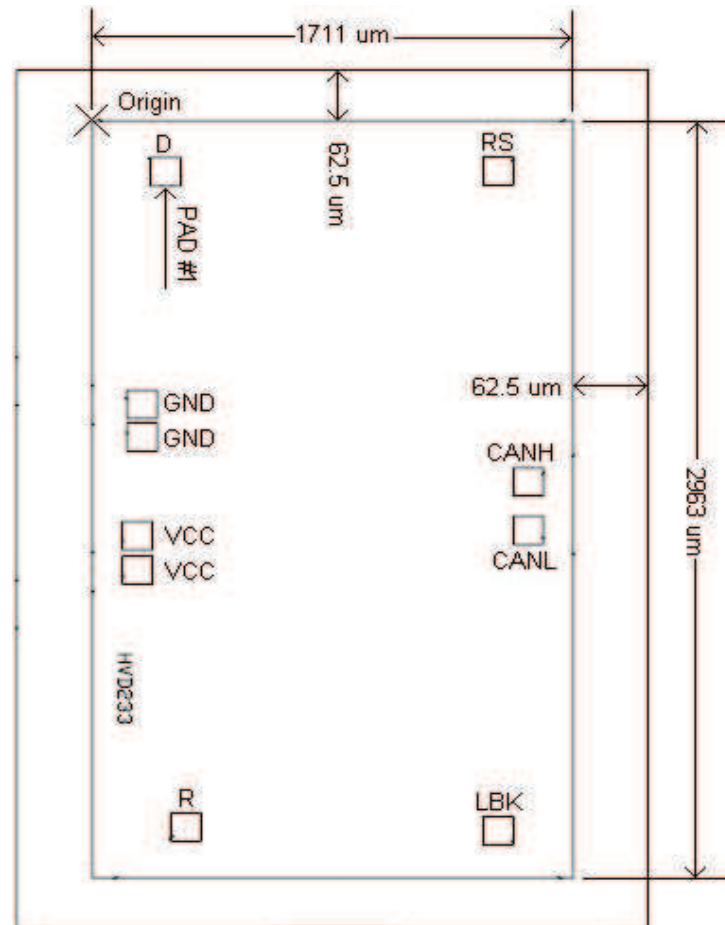
| DIE THICKNESS | BACKSIDE FINISH        | BACKSIDE POTENTIAL | BOND PAD METALLIZATION COMPOSITION |
|---------------|------------------------|--------------------|------------------------------------|
| 15 mils.      | Silicon with backgrind | GND                | Al-Si-Cu (0.5%)                    |

Origin

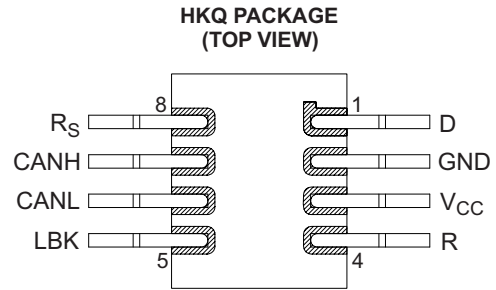
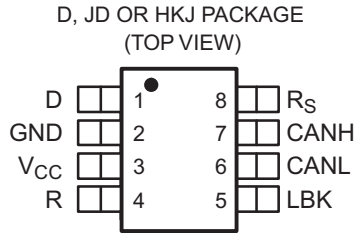


**Table 1. Bond Pad Coordinates in Microns - Rev A**

| DISCRIPTION | PAD NUMBER | a       | b        | c       | d       |
|-------------|------------|---------|----------|---------|---------|
| D           | 1          | 86.40   | 157.85   | 203.40  | 274.85  |
| GND         | 2          | 1035.05 | 69.75    | 1150.05 | 184.75  |
| GND         | 3          | 1168.15 | 69.75    | 1283.15 | 184.75  |
| VCC         | 4          | 1572.05 | 51.85    | 1687.05 | 166.85  |
| VCC         | 5          | 1711.95 | 51.85    | 1826.95 | 166.85  |
| R           | 6          | 2758.85 | 237.65   | 2873.85 | 352.65  |
| LBK         | 7          | 2774.25 | 1429.985 | 2889.25 | 1544.95 |
| CANL        | 8          | 1549.90 | 1544.95  | 1664.90 | 1659.95 |
| CANH        | 9          | 1351.45 | 1544.95  | 1466.45 | 1659.95 |
| RS          | 10         | 83.50   | 1429.95  | 198.50  | 1544.95 |

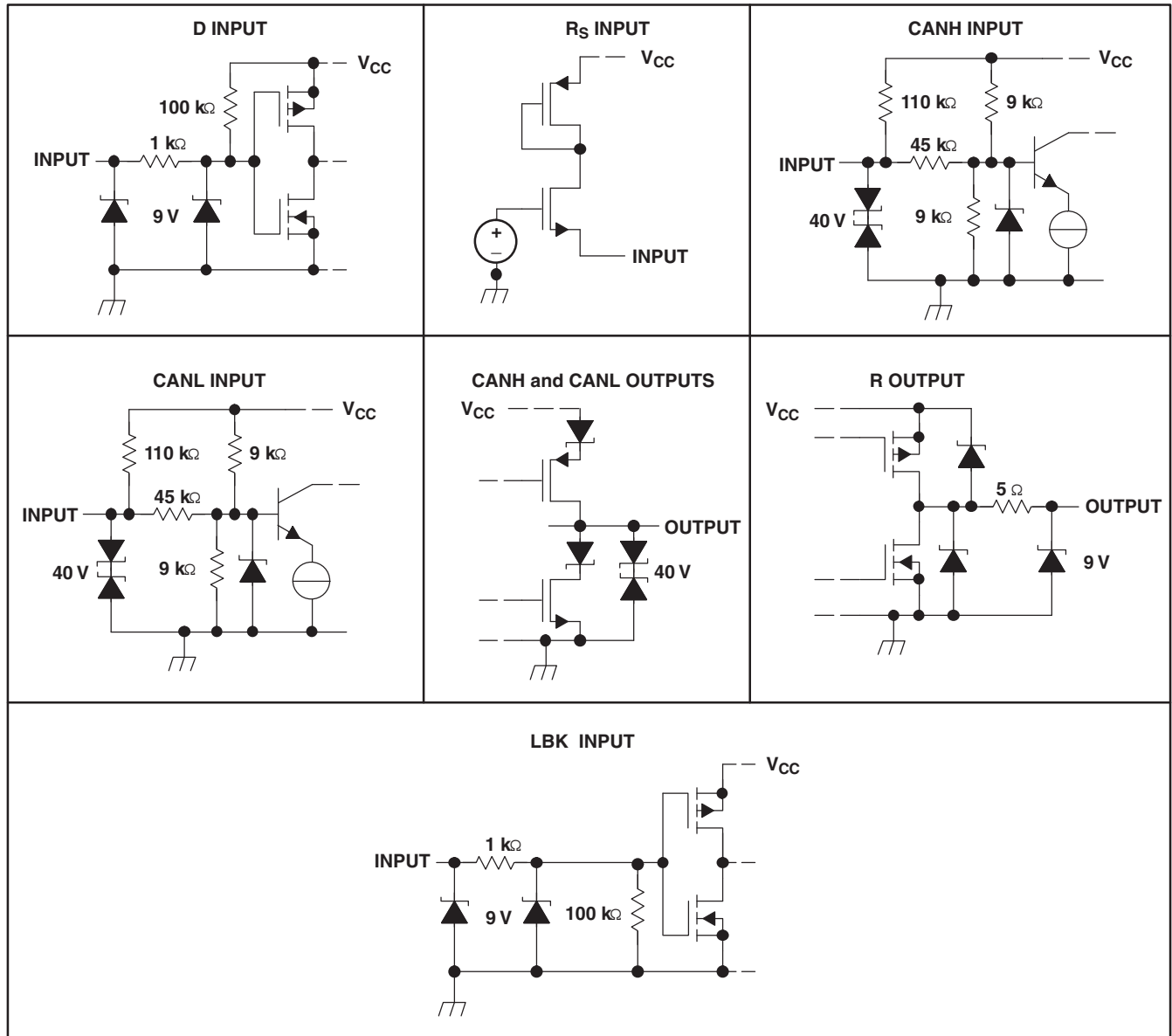


## DEVICE INFORMATION



HKQ as formed or HKJ mounted dead bug

## EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAMS



**FUNCTION TABLES<sup>(1)</sup>**

(1) H = high level, L = low level, Z = high impedance, X = irrelevant, ? = indeterminate

| DRIVER    |           |                    |         |      |           |
|-----------|-----------|--------------------|---------|------|-----------|
| INPUTS    |           |                    | OUTPUTS |      |           |
| D         | LBK       | R <sub>S</sub>     | CANH    | CANL | BUS STATE |
| X         | X         | $>0.75 V_{CC}$     | Z       | Z    | Recessive |
| L         | L or open | $\leq 0.33 V_{CC}$ | H       | L    | Dominant  |
| H or open | X         |                    | Z       | Z    | Recessive |
| X         | H         | $\leq 0.33 V_{CC}$ | Z       | Z    | Recessive |

| RECEIVER  |                                    |           |           |        |
|-----------|------------------------------------|-----------|-----------|--------|
| INPUTS    |                                    |           |           | OUTPUT |
| BUS STATE | $V_{ID} = V_{(CANH)} - V_{(CANL)}$ | LBK       | D         | R      |
| Dominant  | $V_{ID} \geq 0.9 V$                | L or open | X         | L      |
| Recessive | $V_{ID} \leq 0.5 V$ or open        | L or open | H or open | H      |
| ?         | $0.5 V < V_{ID} < 0.9 V$           | L or open | H or open | ?      |
| X         | X                                  | H         | L         | L      |
| X         | X                                  |           | H         | H      |

**ABSOLUTE MAXIMUM RATINGS<sup>(1) (2)</sup>**

over operating free-air temperature range (unless otherwise noted)

|                         |                                                                                          |                     | VALUE       | UNIT |
|-------------------------|------------------------------------------------------------------------------------------|---------------------|-------------|------|
| V <sub>CC</sub>         | Supply voltage range                                                                     |                     | –0.3 to 7   | V    |
|                         | Voltage range at any bus terminal (CANH or CANL)                                         |                     | –36 to 36   | V    |
|                         | Voltage input range, transient pulse (CANH and CANL) through 100 $\Omega$ (see Figure 8) |                     | –100 to 100 | V    |
| V <sub>I</sub>          | Input voltage range (D, R, R <sub>S</sub> , LBK)                                         |                     | –0.5 to 7   | V    |
| I <sub>O</sub>          | Receiver output current                                                                  |                     | –10 to 10   | mA   |
| Electrostatic discharge | Human-Body Model (HBM) <sup>(3)</sup>                                                    | CANH, CANL, and GND | 16          | kV   |
|                         |                                                                                          | All pins            | 3           |      |
|                         | Charged-Device Mode (CDM) <sup>(4)</sup>                                                 | All pins            | 1           |      |

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.
- (3) Tested in accordance with JEDEC Standard 22, Test Method A114-A.
- (4) Tested in accordance with JEDEC Standard 22, Test Method C101.

## THERMAL CHARACTERISTICS FOR D PACKAGE

over operating free-air temperature range (unless otherwise noted)

| PARAMETER     |                                                         | MIN | TYP | MAX | UNIT |
|---------------|---------------------------------------------------------|-----|-----|-----|------|
| $\theta_{JC}$ | Junction-to-case thermal resistance (to bottom of case) |     | 49  |     | °C/W |

## THERMAL CHARACTERISTICS FOR JD PACKAGE

over operating free-air temperature range unless otherwise noted

| PARAMETER     |                                                       | TEST CONDITIONS                                                                                                                 |  | MIN | TYP | MAX  | UNIT |
|---------------|-------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------|--|-----|-----|------|------|
| $\theta_{JA}$ | Junction-to-ambient thermal resistance <sup>(1)</sup> | Low-K <sup>(2)</sup> board, no air flow                                                                                         |  |     |     | 83.4 | °C/W |
|               |                                                       | High-K <sup>(3)</sup> board, no air flow                                                                                        |  |     |     | 64.9 |      |
| $\theta_{JB}$ | Junction-to-board thermal resistance                  | High-K <sup>(3)</sup> board, no air flow                                                                                        |  |     |     | 27.9 | °C/W |
| $\theta_{JC}$ | Junction-to-case thermal resistance                   |                                                                                                                                 |  |     |     | 6.49 | °C/W |
| $P_{(AVG)}$   | Average power dissipation                             | $R_L = 60\ \Omega$ , $R_S = 0\ V$ , input to D a 1-MHz 50% duty cycle square wave, $V_{CC} = 3.3\ V$ , $T_A = 25^\circ\text{C}$ |  |     |     | 114  | mW   |

(1) See TI literature number [SZZA003](#) for an explanation of this parameter.

(2) JESD51-3 low effective thermal conductivity test board for leaded surface-mount packages.

(3) JESD51-7 high effective thermal conductivity test board for leaded surface-mount packages.

## THERMAL CHARACTERISTICS FOR HKJ OR HKQ PACKAGE

over operating free-air temperature range (unless otherwise noted)

| PARAMETER     |                                     |                                         | MIN | TYP | MAX  | UNIT |
|---------------|-------------------------------------|-----------------------------------------|-----|-----|------|------|
| $\theta_{JC}$ | Junction-to-case thermal resistance | to ceramic side of case                 |     |     | 5.7  | °C/W |
|               |                                     | to top of case lid (metal side of case) |     |     | 13.7 |      |

## RECOMMENDED OPERATING CONDITIONS

|             |                                                         |          |  | $T_A = -55^\circ\text{C to } 210^\circ\text{C}$ |     | UNIT       |
|-------------|---------------------------------------------------------|----------|--|-------------------------------------------------|-----|------------|
|             |                                                         |          |  | MIN                                             | MAX |            |
| $V_{CC}$    | Supply voltage                                          |          |  | 3                                               | 3.6 | V          |
|             | Voltage at any bus terminal (separately or common mode) |          |  | –7                                              | 12  | V          |
| $V_{IH}$    | High-level input voltage                                | D, LBK   |  | 2                                               | 5.5 | V          |
| $V_{IL}$    | Low-level input voltage                                 | D, LBK   |  | 0                                               | 0.8 | V          |
| $V_{ID}$    | Differential input voltage                              |          |  | –6                                              | 6   | V          |
|             | Resistance from $R_S$ to ground                         |          |  | 0                                               | 100 | k $\Omega$ |
| $V_{I(RS)}$ | Input voltage at $R_S$ for standby                      |          |  | $0.75\ V_{CC}$                                  | 5.5 | V          |
| $I_{OH}$    | High-level output current                               | Driver   |  | –50                                             |     | mA         |
|             |                                                         | Receiver |  | –10                                             |     |            |
| $I_{OL}$    | Low-level output current                                | Driver   |  |                                                 | 50  | mA         |
|             |                                                         | Receiver |  |                                                 | 10  |            |
| $T_J$       | Operating junction temperature                          |          |  |                                                 | 212 | °C         |
| $T_A$       | Operating free-air temperature <sup>(1)</sup>           |          |  | –55                                             | 210 | °C         |

(1) Maximum free-air temperature operation is allowed as long as the device maximum junction temperature is not exceeded.

## DRIVER ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

| PARAMETER           |                                          |           | TEST CONDITIONS                                                                             | T <sub>A</sub> = –55°C to 125°C |     |                 | T <sub>A</sub> = 175°C <sup>(1)</sup> |      |                 | T <sub>A</sub> = 210°C <sup>(2)</sup> |      |                 | UNIT |
|---------------------|------------------------------------------|-----------|---------------------------------------------------------------------------------------------|---------------------------------|-----|-----------------|---------------------------------------|------|-----------------|---------------------------------------|------|-----------------|------|
|                     |                                          |           |                                                                                             | MIN                             | TYP | MAX             | MIN                                   | TYP  | MAX             | MIN                                   | TYP  | MAX             |      |
| V <sub>O(D)</sub>   | Bus output voltage (dominant)            | CANH      | D = 0 V, R <sub>S</sub> = 0 V,<br>See <a href="#">Figure 2</a> and <a href="#">Figure 3</a> | 2.45                            |     | V <sub>CC</sub> | 2.45                                  |      | V <sub>CC</sub> | 2.45                                  |      | V <sub>CC</sub> | V    |
|                     |                                          | CANL      |                                                                                             | 0.5                             |     | 1.25            | 0.5                                   |      | 1.25            | 0.5                                   |      | 1.25            |      |
| V <sub>O</sub>      | Bus output voltage (recessive)           | CANH      | D = 3 V, R <sub>S</sub> = 0 V,<br>See <a href="#">Figure 2</a> and <a href="#">Figure 3</a> | 2.3                             |     |                 | 2.3                                   |      |                 | 2.3                                   |      |                 | V    |
|                     |                                          | CANL      |                                                                                             | 2.3                             |     |                 | 2.3                                   |      |                 | 2.3                                   |      |                 |      |
| V <sub>OD(D)</sub>  | Differential output voltage (Dominant)   |           | D = 0 V, R <sub>S</sub> = 0 V,<br>See <a href="#">Figure 2</a> and <a href="#">Figure 3</a> | 1.5                             | 2   | 3               | 1.4                                   | 1.75 | 3               | 1.4                                   | 1.75 | 3               | V    |
|                     |                                          |           | D = 0 V, R <sub>S</sub> = 0 V,<br>See <a href="#">Figure 3</a> and <a href="#">Figure 4</a> | 1.1                             | 2   | 3               | 1.1                                   | 1.47 | 3               | 1.1                                   | 1.47 | 3               |      |
| V <sub>OD</sub>     | Differential output voltage (Recessive)  |           | D = 3 V, R <sub>S</sub> = 0 V,<br>See <a href="#">Figure 2</a> and <a href="#">Figure 3</a> | –120                            |     | 12              | –120                                  |      | 12              | –120                                  |      | 12              | mV   |
|                     |                                          |           | D = 3 V, R <sub>S</sub> = 0 V, No load                                                      | –0.5                            |     | 0.05            | –0.5                                  |      | 0.8             | –0.5                                  |      | 1.2             | V    |
| V <sub>OC(pp)</sub> | Peak-to-peak common-mode output voltage  |           | See <a href="#">Figure 10</a>                                                               | 1                               |     |                 | 1                                     |      |                 | 1                                     |      |                 | V    |
| I <sub>IH</sub>     | High-level input current                 | D, LBK    | D = 2 V                                                                                     | –30                             |     | 30              | –30                                   |      | 30              | –30                                   |      | 30              | μA   |
| I <sub>IL</sub>     | Low-level input current                  | D, LBK    | D = 0.8 V                                                                                   | –30                             |     | 30              | –30                                   |      | 30              | –30                                   |      | 30              | μA   |
| I <sub>OS</sub>     | Short-circuit output current             |           | V <sub>CANH</sub> = –7 V,<br>CANL open,<br>See <a href="#">Figure 13</a>                    | –250                            |     |                 | –250                                  |      |                 | –250                                  |      |                 | mA   |
|                     |                                          |           | V <sub>CANH</sub> = 12 V,<br>CANL open,<br>See <a href="#">Figure 13</a>                    | 1                               |     |                 | 1                                     |      |                 | 1                                     |      |                 |      |
|                     |                                          |           | V <sub>CANL</sub> = –7 V,<br>CANH open,<br>See <a href="#">Figure 13</a>                    | –1                              |     |                 | –1                                    |      |                 | –1                                    |      |                 |      |
|                     |                                          |           | V <sub>CANL</sub> = 12 V,<br>CANH open,<br>See <a href="#">Figure 13</a>                    | 250                             |     |                 | 250                                   |      |                 | 250                                   |      |                 |      |
| C <sub>O</sub>      | Output capacitance                       |           | See receiver input capacitance                                                              |                                 |     |                 |                                       |      |                 |                                       |      |                 |      |
| I <sub>IRS(s)</sub> | R <sub>S</sub> input current for standby |           | R <sub>S</sub> = 0.75 V <sub>CC</sub>                                                       | –10                             |     |                 | –10                                   |      |                 | –10                                   |      |                 | μA   |
| I <sub>CC</sub>     | Supply current                           | Standby   | R <sub>S</sub> = V <sub>CC</sub> , D = V <sub>CC</sub> ,<br>LBK = 0 V                       | 200                             |     | 600             | 400                                   |      | 600             | 400                                   |      | 600             | μA   |
|                     |                                          | Dominant  | D = 0 V, No load,<br>LBK = 0 V, R <sub>S</sub> = 0 V                                        | 6                               |     |                 | 6                                     |      |                 | 6                                     |      |                 | mA   |
|                     |                                          | Recessive | D = V <sub>CC</sub> , No load,<br>LBK = 0 V, R <sub>S</sub> = 0 V                           | 6                               |     |                 | 6                                     |      |                 | 6                                     |      |                 |      |

(1) Minimum and maximum parameters are characterized for operation at T<sub>A</sub> = 175°C and production tested at T<sub>A</sub> = 125°C.

(2) Minimum and maximum parameters are characterized for operation at T<sub>A</sub> = 210°C but may not be production tested at that temperature. Production test limits with statistical guardbands are used to ensure high temperature performance.

## DRIVER SWITCHING CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

| PARAMETER                                                  | TEST CONDITIONS                                                   | $T_A = -55^{\circ}\text{C to } 125^{\circ}\text{C}$ |     |      | $T_A = 175^{\circ}\text{C}^{(1)}$ |     |      | $T_A = 210^{\circ}\text{C}^{(2)}$ |     |      | UNIT          |
|------------------------------------------------------------|-------------------------------------------------------------------|-----------------------------------------------------|-----|------|-----------------------------------|-----|------|-----------------------------------|-----|------|---------------|
|                                                            |                                                                   | MIN                                                 | TYP | MAX  | MIN                               | TYP | MAX  | MIN                               | TYP | MAX  |               |
| $t_{PLH}$ Propagation delay time, low-to-high-level output | $R_S = 0\text{ V}$ , See <a href="#">Figure 5</a>                 |                                                     | 35  | 85   |                                   | 50  |      |                                   | 50  |      | ns            |
|                                                            | $R_S$ with 10 k $\Omega$ to ground, See <a href="#">Figure 5</a>  |                                                     | 70  | 125  |                                   | 75  |      |                                   | 75  |      |               |
|                                                            | $R_S$ with 100 k $\Omega$ to ground, See <a href="#">Figure 5</a> |                                                     | 500 | 870  |                                   | 500 |      |                                   | 500 |      |               |
| $t_{PHL}$ Propagation delay time, high-to-low-level output | $R_S = 0\text{ V}$ , See <a href="#">Figure 5</a>                 |                                                     | 70  | 120  |                                   | 70  |      |                                   | 70  |      | ns            |
|                                                            | $R_S$ with 10 k $\Omega$ to ground, See <a href="#">Figure 5</a>  |                                                     | 130 | 180  |                                   | 130 |      |                                   | 130 |      |               |
|                                                            | $R_S$ with 100 k $\Omega$ to ground, See <a href="#">Figure 5</a> |                                                     | 870 | 1200 |                                   | 870 |      |                                   | 870 |      |               |
| $t_{sk(p)}$ Pulse skew ( $ t_{PHL} - t_{PLH} $ )           | $R_S = 0\text{ V}$ , See <a href="#">Figure 5</a>                 |                                                     | 35  |      |                                   | 9   |      |                                   | 9   |      | ns            |
|                                                            | $R_S$ with 10 k $\Omega$ to ground, See <a href="#">Figure 5</a>  |                                                     | 60  |      |                                   | 35  |      |                                   | 35  |      |               |
|                                                            | $R_S$ with 100 k $\Omega$ to ground, See <a href="#">Figure 5</a> |                                                     | 370 |      |                                   | 475 |      |                                   | 475 |      |               |
| $t_r$ Differential output signal rise time                 | $R_S = 0\text{ V}$ , See <a href="#">Figure 5</a>                 | 20                                                  |     | 70   | 20                                |     | 75   | 20                                |     | 75   | ns            |
| $t_f$ Differential output signal fall time                 |                                                                   | 18                                                  |     | 70   | 20                                |     | 75   | 20                                |     | 75   |               |
| $t_r$ Differential output signal rise time                 | $R_S$ with 10 k $\Omega$ to ground, See <a href="#">Figure 5</a>  | 30                                                  |     | 135  | 30                                |     | 140  | 30                                |     | 140  | ns            |
| $t_f$ Differential output signal fall time                 |                                                                   | 30                                                  |     | 135  | 30                                |     | 140  | 30                                |     | 140  |               |
| $t_r$ Differential output signal rise time                 | $R_S$ with 100 k $\Omega$ to ground, See <a href="#">Figure 5</a> | 250                                                 |     | 1400 | 250                               |     | 1400 | 250                               |     | 1400 | ns            |
| $t_f$ Differential output signal fall time                 |                                                                   | 350                                                 |     | 1400 | 350                               |     | 1400 | 350                               |     | 1400 |               |
| $t_{en(s)}$ Enable time from standby to dominant           | See <a href="#">Figure 9</a>                                      |                                                     | 0.6 | 1.5  |                                   | 0.6 | 1.5  |                                   | 0.6 | 1.5  | $\mu\text{s}$ |

- (1) Minimum and maximum parameters are characterized for operation at  $T_A = 210^{\circ}\text{C}$  but not production tested at  $T_A = 175^{\circ}\text{C}$  or  $210^{\circ}\text{C}$ .
- (2) Minimum and maximum parameters are characterized for operation at  $T_A = 210^{\circ}\text{C}$  but may not be production tested at that temperature. Production test limits with statistical guardbands are used to ensure high temperature performance.

## RECEIVER ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

| PARAMETER                                            | TEST CONDITIONS                                     | $T_A = -55^{\circ}\text{C to } 125^{\circ}\text{C}$ |     |     | $T_A = 175^{\circ}\text{C}^{(1)}$ |     |     | $T_A = 210^{\circ}\text{C}^{(2)}$ |     |     | UNIT |
|------------------------------------------------------|-----------------------------------------------------|-----------------------------------------------------|-----|-----|-----------------------------------|-----|-----|-----------------------------------|-----|-----|------|
|                                                      |                                                     | MIN                                                 | TYP | MAX | MIN                               | TYP | MAX | MIN                               | TYP | MAX |      |
| $V_{IT+}$ Positive-going input threshold voltage     | LBK = 0 V, See <a href="#">Table 2</a>              |                                                     | 620 | 900 |                                   | 600 | 900 |                                   | 600 | 900 | mV   |
| $V_{IT-}$ Negative-going input threshold voltage     |                                                     | 500                                                 | 715 |     | 500                               | 725 |     | 500                               | 725 |     | mV   |
| $V_{hys}$ Hysteresis voltage ( $V_{IT+} - V_{IT-}$ ) |                                                     |                                                     | 100 |     |                                   | 140 |     |                                   | 140 |     | mV   |
| $V_{OH}$ High-level output voltage                   | $I_O = -4\text{ mA}$ , See <a href="#">Figure 7</a> | 2.4                                                 |     |     | 2.4                               |     |     | 2.4                               |     |     | V    |

- (1) Minimum and maximum parameters are characterized for operation at  $T_A = 210^{\circ}\text{C}$  and are not characterized or production tested at  $T_A = 175^{\circ}\text{C}$ .
- (2) Minimum and maximum parameters are characterized for operation at  $T_A = 210^{\circ}\text{C}$  but may not be production tested at that temperature. Production test limits with statistical guardbands are used to ensure high temperature performance.

**RECEIVER ELECTRICAL CHARACTERISTICS (continued)**

over operating free-air temperature range (unless otherwise noted)

| PARAMETER       |                                  | TEST CONDITIONS                                                               | T <sub>A</sub> = –55°C to 125°C |     |      | T <sub>A</sub> = 175°C <sup>(1)</sup> |     |      | T <sub>A</sub> = 210°C <sup>(2)</sup> |     |      | UNIT |
|-----------------|----------------------------------|-------------------------------------------------------------------------------|---------------------------------|-----|------|---------------------------------------|-----|------|---------------------------------------|-----|------|------|
|                 |                                  |                                                                               | MIN                             | TYP | MAX  | MIN                                   | TYP | MAX  | MIN                                   | TYP | MAX  |      |
| V <sub>OL</sub> | Low-level output voltage         | I <sub>O</sub> = 4 mA, See <a href="#">Figure 7</a>                           |                                 |     | 0.4  |                                       |     | 0.4  |                                       |     | 0.4  | V    |
| I <sub>I</sub>  | Bus input current                | CANH or CANL = 12 V                                                           | 140                             |     | 500  | 140                                   |     | 500  | 140                                   |     | 500  | μA   |
|                 |                                  | CANH or CANL = 12 V, V <sub>CC</sub> = 0 V                                    | 200                             |     | 600  | 200                                   |     | 700  | 200                                   |     | 800  |      |
|                 |                                  | CANH or CANL = –7 V                                                           | –610                            |     | –150 | –610                                  |     | –150 | –610                                  |     | –150 |      |
|                 |                                  | CANH or CANL = –7 V, V <sub>CC</sub> = 0 V                                    | –450                            |     | –130 | –450                                  |     | –130 | –450                                  |     | –130 |      |
| C <sub>I</sub>  | Input capacitance (CANH or CANL) | Pin to ground, V <sub>I</sub> = 0.4 sin (4E6πt) + 0.5 V, D = 3 V, LBK = 0 V   |                                 | 45  |      |                                       | 55  |      |                                       | 55  |      | pF   |
| C <sub>ID</sub> | Differential input capacitance   | Pin to pin, V <sub>I</sub> = 0.4 sin (4E6πt) + 0.5 V, D = 3 V, LBK = 0 V      |                                 | 15  |      |                                       | 15  |      |                                       | 15  |      | pF   |
| R <sub>ID</sub> | Differential input resistance    | D = 3 V, LBK = 0 V                                                            | 40                              |     | 110  | 40                                    |     | 110  | 40                                    |     | 110  | kΩ   |
| R <sub>IN</sub> | Input resistance (CANH or CANL)  |                                                                               | 20                              |     | 51   | 19                                    |     | 51   | 18                                    |     | 51   | kΩ   |
| I <sub>CC</sub> | Supply current                   | Standby<br>R <sub>S</sub> = V <sub>CC</sub> , D = V <sub>CC</sub> , LBK = 0 V |                                 | 200 | 600  |                                       | 400 | 600  |                                       | 400 | 600  | μA   |
|                 |                                  | Dominant<br>D = 0 V, No load, R <sub>S</sub> = 0 V, LBK = 0 V                 |                                 |     | 6    |                                       |     | 6    |                                       |     | 6    | mA   |
|                 |                                  | Recessive<br>D = V <sub>CC</sub> , No load, R <sub>S</sub> = 0 V, LBK = 0 V   |                                 |     | 6    |                                       |     | 6    |                                       |     | 6    |      |

## RECEIVER SWITCHING CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

| PARAMETER                                                  | TEST CONDITIONS              | $T_A = -55^{\circ}\text{C to } 125^{\circ}\text{C}$ |     |     | $T_A = 175^{\circ}\text{C}^{(1)}$ |     |     | $T_A = 210^{\circ}\text{C}^{(2)}$ |     |     | UNIT |
|------------------------------------------------------------|------------------------------|-----------------------------------------------------|-----|-----|-----------------------------------|-----|-----|-----------------------------------|-----|-----|------|
|                                                            |                              | MIN                                                 | TYP | MAX | MIN                               | TYP | MAX | MIN                               | TYP | MAX |      |
| $t_{PLH}$ Propagation delay time, low-to-high-level output | See <a href="#">Figure 7</a> |                                                     | 35  | 60  |                                   | 50  | 60  |                                   | 50  | 60  | ns   |
| $t_{PHL}$ Propagation delay time, high-to-low-level output |                              |                                                     | 35  | 60  |                                   | 45  | 60  |                                   | 45  | 60  | ns   |
| $t_{sk(p)}$ Pulse skew ( $t_{PHL} - t_{PLH}$ )             |                              |                                                     | 7   |     |                                   | 5   |     |                                   | 5   |     | ns   |
| $t_r$ Output signal rise time                              |                              |                                                     | 2   | 6.5 |                                   | 6.5 | 8   |                                   | 6.5 | 8   | ns   |
| $t_f$ Output signal fall time                              |                              |                                                     | 2   | 6.5 |                                   | 6.5 | 9   |                                   | 6.5 | 9   | ns   |

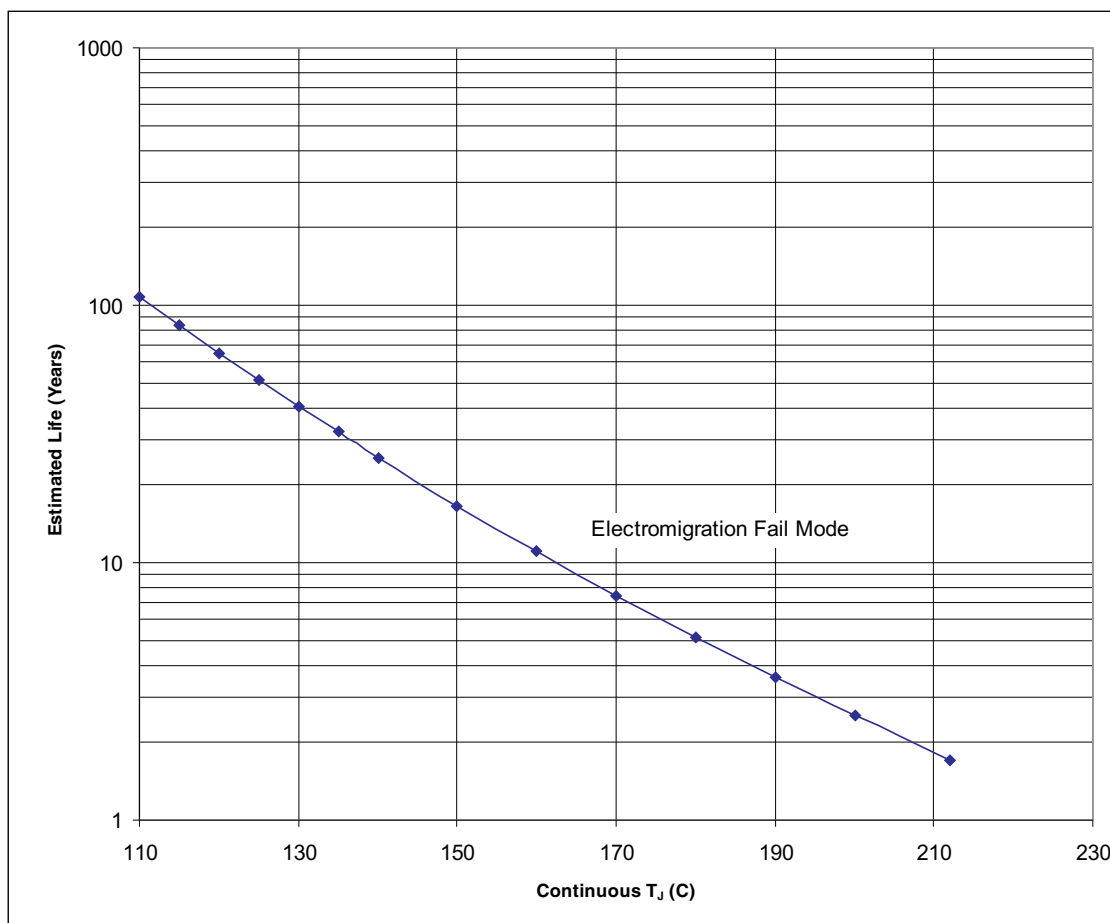
- (1) Minimum and maximum parameters are characterized for operation at  $T_A = 210^{\circ}\text{C}$  but not production tested at  $T_A = 175^{\circ}\text{C}$  or  $210^{\circ}\text{C}$ .  
(2) Minimum and maximum parameters are characterized for operation at  $T_A = 210^{\circ}\text{C}$  but may not be production tested at that temperature. Production test limits with statistical guardbands are used to ensure high temperature performance.

## DEVICE SWITCHING CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

| PARAMETER                                                                              | TEST CONDITIONS                                                    | $T_A = -55^{\circ}\text{C to } 125^{\circ}\text{C}$ |     |      | $T_A = 175^{\circ}\text{C}^{(1)}$ |     |      | $T_A = 210^{\circ}\text{C}^{(2)}$ |     |      | UNIT |
|----------------------------------------------------------------------------------------|--------------------------------------------------------------------|-----------------------------------------------------|-----|------|-----------------------------------|-----|------|-----------------------------------|-----|------|------|
|                                                                                        |                                                                    | MIN                                                 | TYP | MAX  | MIN                               | TYP | MAX  | MIN                               | TYP | MAX  |      |
| $t_{(LBK)}$ Loopback delay, driver input to receiver output                            | See <a href="#">Figure 12</a>                                      |                                                     | 7.5 | 15   |                                   | 12  | 15   |                                   | 12  | 15   | ns   |
| $t_{(loop1)}$ Total loop delay, driver input to receiver output, recessive to dominant | $R_S = 0\text{ V}$ , See <a href="#">Figure 11</a>                 |                                                     | 70  | 135  |                                   | 90  | 135  |                                   | 90  | 135  | ns   |
|                                                                                        | $R_S$ with 10 k $\Omega$ to ground, See <a href="#">Figure 11</a>  |                                                     | 105 | 190  |                                   | 115 | 190  |                                   | 115 | 190  |      |
|                                                                                        | $R_S$ with 100 k $\Omega$ to ground, See <a href="#">Figure 11</a> |                                                     | 535 | 1000 |                                   | 430 | 1000 |                                   | 430 | 1000 |      |
| $t_{(loop2)}$ Total loop delay, driver input to receiver output, dominant to recessive | $R_S = 0\text{ V}$ , See <a href="#">Figure 11</a>                 |                                                     | 70  | 135  |                                   | 98  | 135  |                                   | 98  | 135  | ns   |
|                                                                                        | $R_S$ with 10 k $\Omega$ to ground, See <a href="#">Figure 11</a>  |                                                     | 105 | 190  |                                   | 150 | 190  |                                   | 150 | 190  |      |
|                                                                                        | $R_S$ with 100 k $\Omega$ to ground, See <a href="#">Figure 11</a> |                                                     | 535 | 1100 |                                   | 880 | 1200 |                                   | 880 | 1200 |      |

- (1) Minimum and maximum parameters are characterized for operation at  $T_A = 210^{\circ}\text{C}$  but not production tested at  $T_A = 175^{\circ}\text{C}$  or  $210^{\circ}\text{C}$ .  
(2) Minimum and maximum parameters are characterized for operation at  $T_A = 210^{\circ}\text{C}$  but may not be production tested at that temperature. Production test limits with statistical guardbands are used to ensure high temperature performance.



- A. See data sheet for absolute maximum and minimum recommended operating conditions.
- B. Silicon operating life design goal is 10 years at 105°C junction temperature (does not include package interconnect life).

**Figure 1. SN65HVD233HD/SN65HVD233SJD/SN65HVD233SKGDA/SN65HVD233SHKJ/SN65HVD233SHKQ  
Operating Life Derating Chart**

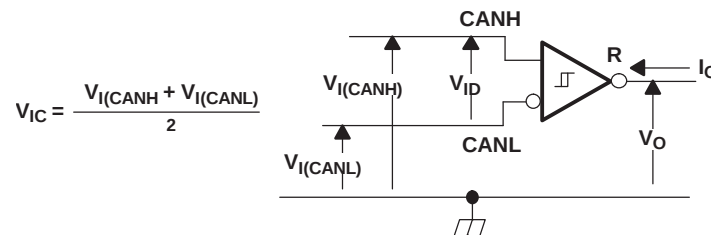
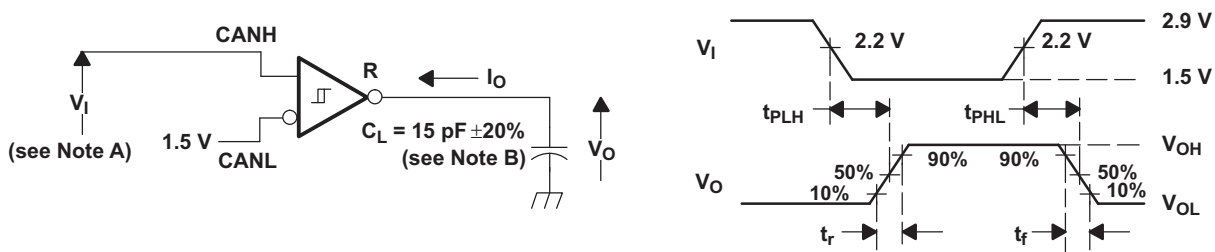
Figure 1 shows the test circuit and timing diagram for the output voltage  $V_O$ .

**Test Circuit:** The circuit consists of an op-amp configured as a voltage follower. The input  $V_I$  is applied to the non-inverting input. The output  $V_O$  is connected to the inverting input through a resistor  $R_S$ . The load capacitor  $C_L$  is connected between the output and the inverting input. The load resistor  $R_L$  is connected between the output and ground. The output voltage  $V_O$  is measured across the load capacitor  $C_L$ .

**Timing Diagram:** The timing diagram shows the input voltage  $V_I$  and the output voltage  $V_O$  over time. The input  $V_I$  transitions from  $V_{CC}/2$  to  $0\text{ V}$  and back to  $V_{CC}/2$ . The output  $V_O$  transitions from  $0.9\text{ V}$  to  $0.5\text{ V}$  and back to  $0.9\text{ V}$ . The timing parameters are defined as follows:

- $t_{PLH}$ : Propagation delay from  $V_I$  rising to  $V_O$  rising.
- $t_{PHL}$ : Propagation delay from  $V_I$  falling to  $V_O$  falling.
- $t_r$ : Rise time of  $V_O$  from 10% to 90% of the final value.
- $t_f$ : Fall time of  $V_O$  from 90% to 10% of the final value.

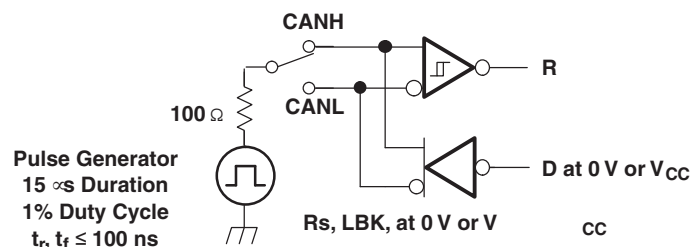
- ### Figure 5. Driver Test Circuit and Voltage Waveforms

**PARAMETER MEASUREMENT INFORMATION (continued)****Figure 6. Receiver Voltage and Current Definitions**

- A. The input pulse is supplied by a generator having the following characteristics: Pulse repetition rate (PRR)  $\leq 125$  kHz, 50% duty cycle,  $t_r \leq 6$  ns,  $t_f \leq 6$  ns,  $Z_O = 50 \Omega$ .
- B.  $C_L$  includes fixture and instrumentation capacitance.

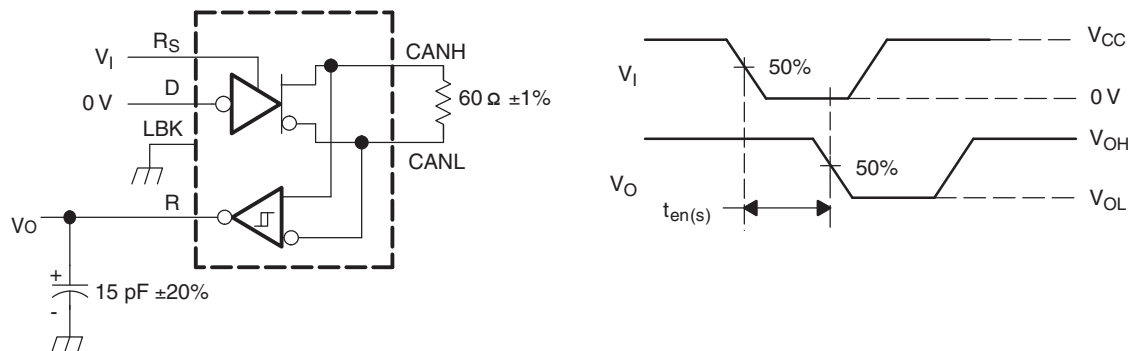
**Figure 7. Receiver Test Circuit and Voltage Waveforms****Table 2. Differential Input Voltage Threshold Test**

| INPUT             |                   | OUTPUT |                 | MEASURED        |
|-------------------|-------------------|--------|-----------------|-----------------|
| V <sub>CANH</sub> | V <sub>CANL</sub> | R      |                 | V <sub>ID</sub> |
| −6.1 V            | −7 V              | L      | V <sub>OL</sub> | 900 mV          |
| 12 V              | 11.1 V            | L      |                 | 900 mV          |
| −1 V              | −7 V              | L      |                 | 6 V             |
| 12 V              | 6 V               | L      |                 | 6 V             |
| −6.5 V            | −7 V              | H      | V <sub>OH</sub> | 500 mV          |
| 12 V              | 11.5 V            | H      |                 | 500 mV          |
| −7 V              | −1 V              | H      |                 | 6 V             |
| 6 V               | 12 V              | H      |                 | 6 V             |
| Open              | Open              | H      |                 | X               |



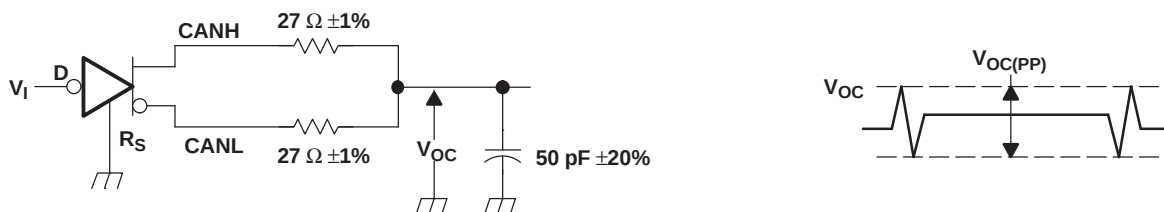
NOTE: This test is conducted to test survivability only. Data stability at the R output is not specified.

**Figure 8. Test Circuit, Transient Over Voltage Test**



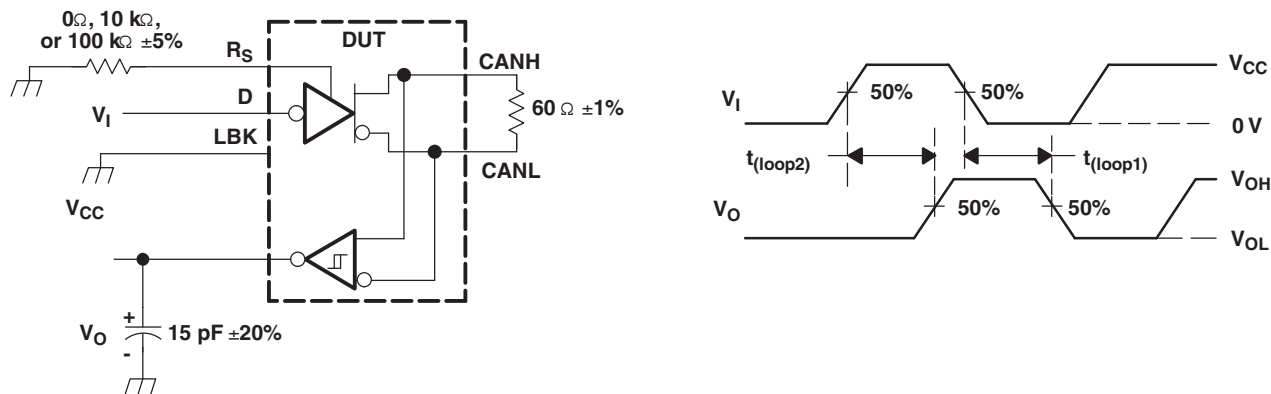
NOTE: All  $V_I$  input pulses are supplied by a generator having the following characteristics:  
 $t_r$  or  $t_f \leq 6$  ns, pulse repetition rate (PRR) = 125 kHz, 50% duty cycle.

**Figure 9.  $t_{en(s)}$  Test Circuit and Voltage Waveforms**



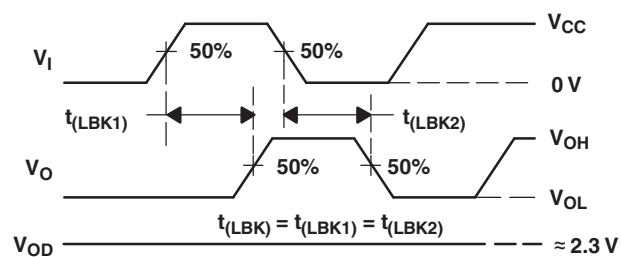
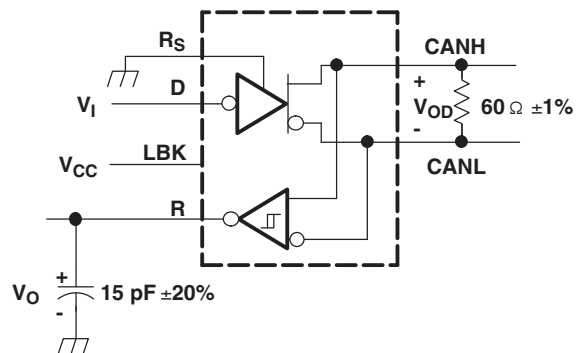
NOTE: All  $V_I$  input pulses are supplied by a generator having the following characteristics:  
 $t_r$  or  $t_f \leq 6$  ns, pulse repetition rate (PRR) = 125 kHz, 50% duty cycle.

**Figure 10.  $V_{OC(pp)}$  Test Circuit and Voltage Waveforms**



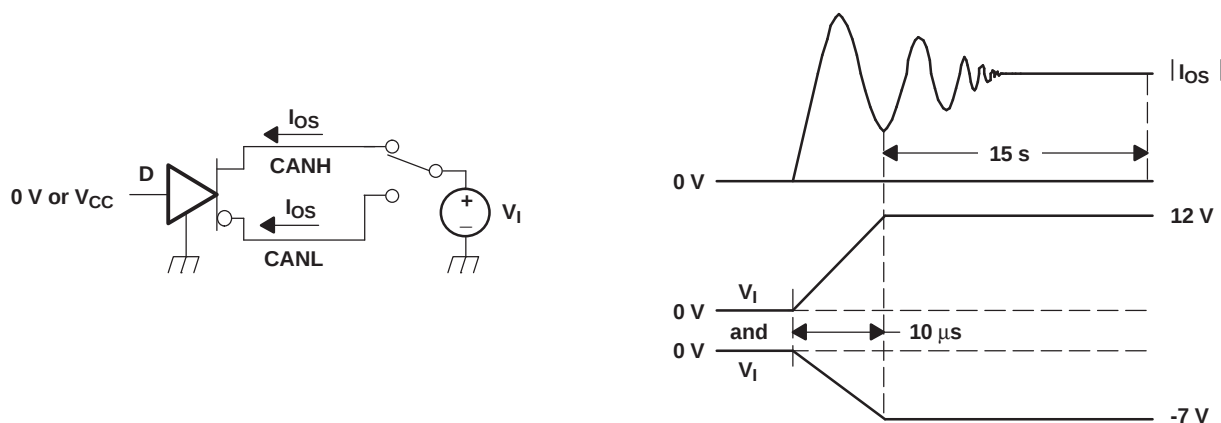
NOTE: All  $V_I$  input pulses are supplied by a generator having the following characteristics:  
 $t_r$  or  $t_f \leq 6$  ns, pulse repetition rate (PRR) = 125 kHz, 50% duty cycle.

**Figure 11.  $t_{loop}$  Test Circuit and Voltage Waveforms**

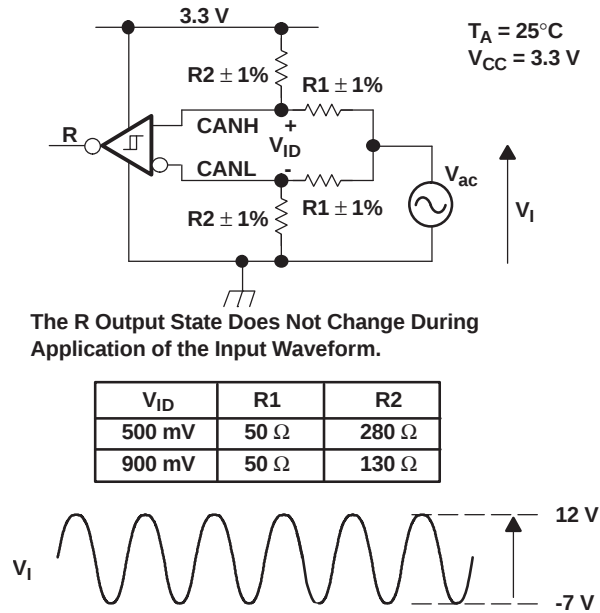


NOTE: All  $V_I$  input pulses are supplied by a generator having the following characteristics:  
 $t_r$  or  $t_f \leq 6$  ns, pulse repetition rate (PRR) = 125 kHz, 50% duty cycle.

**Figure 12.  $t_{LBK}$  Test Circuit and Voltage Waveforms**



**Figure 13.  $I_{OS}$  Test Circuit and Waveforms**



NOTE: All input pulses are supplied by a generator with  $f \leq 1.5\text{ MHz}$ .

**Figure 14. Common-Mode Voltage Rejection**

## TYPICAL CHARACTERISTICS

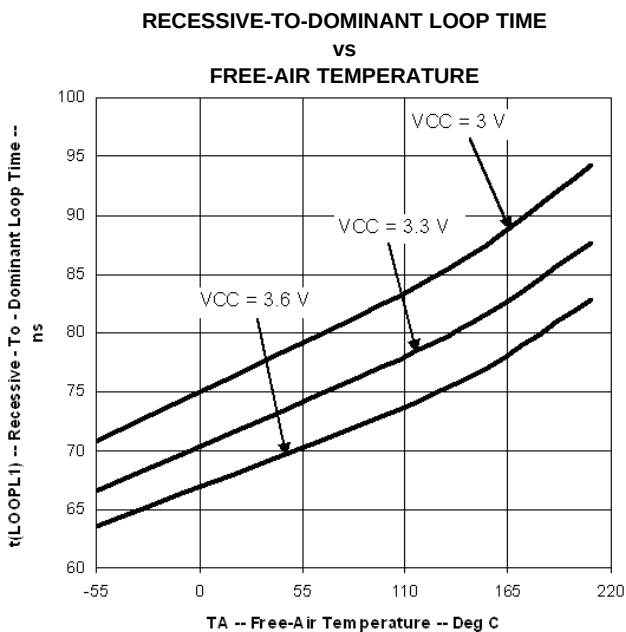


Figure 15.

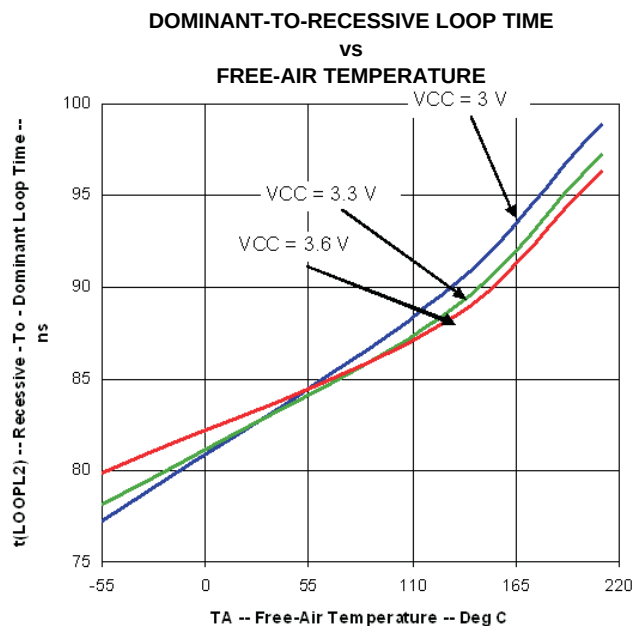


Figure 16.

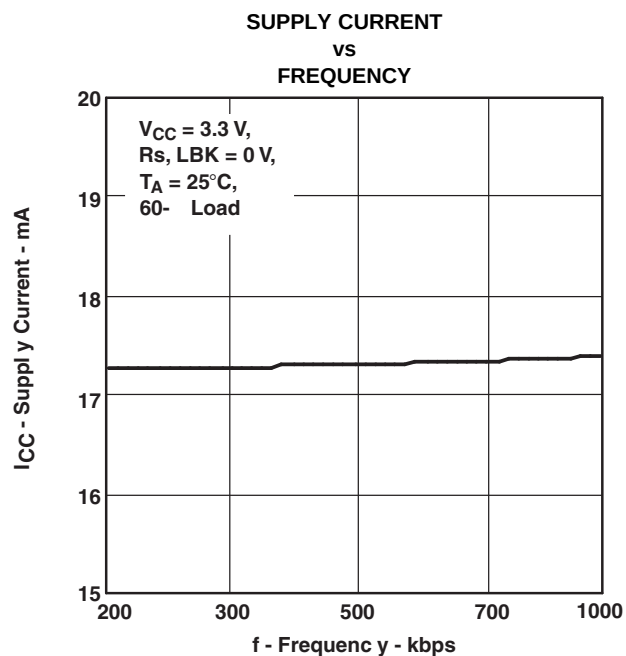


Figure 17.

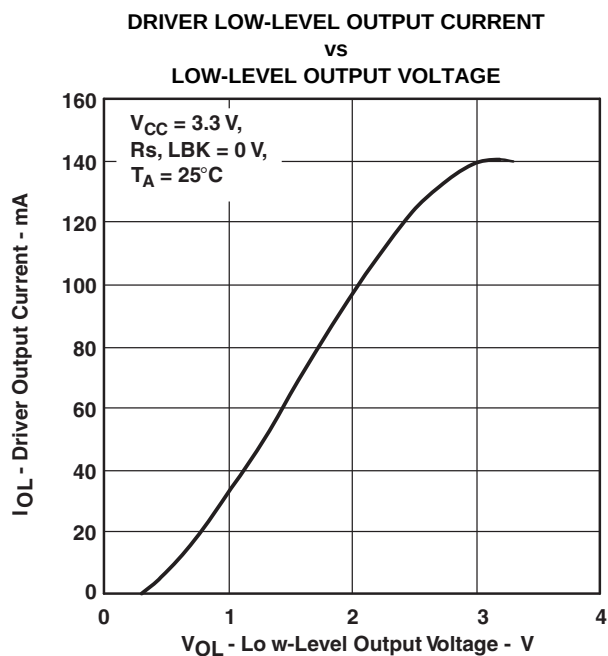
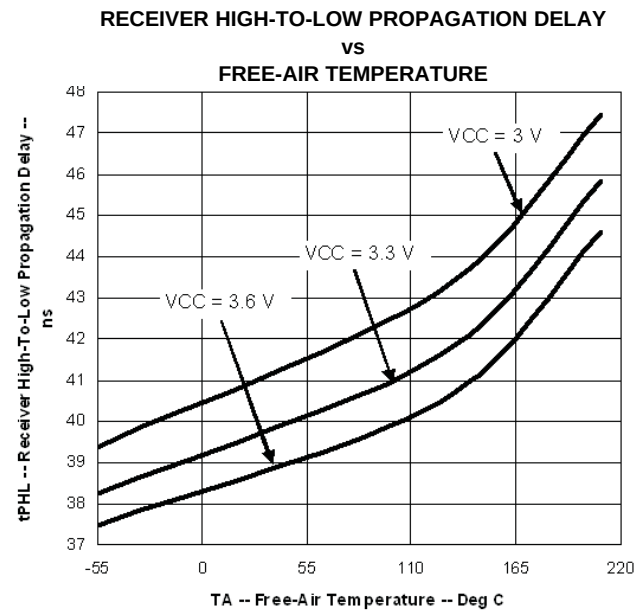
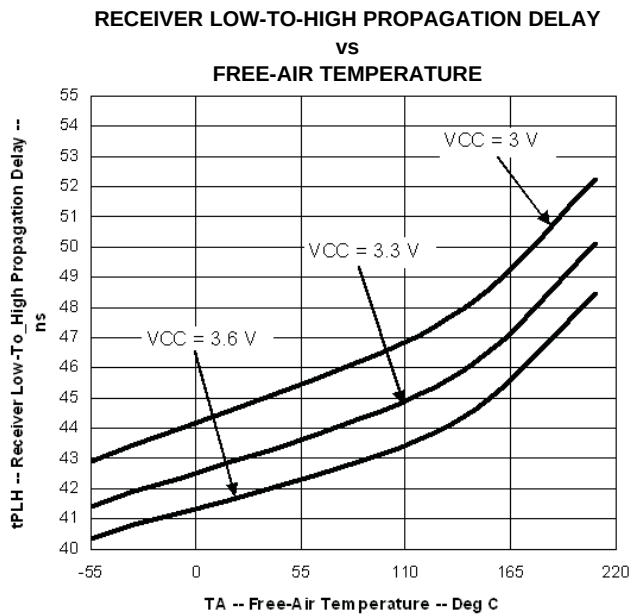
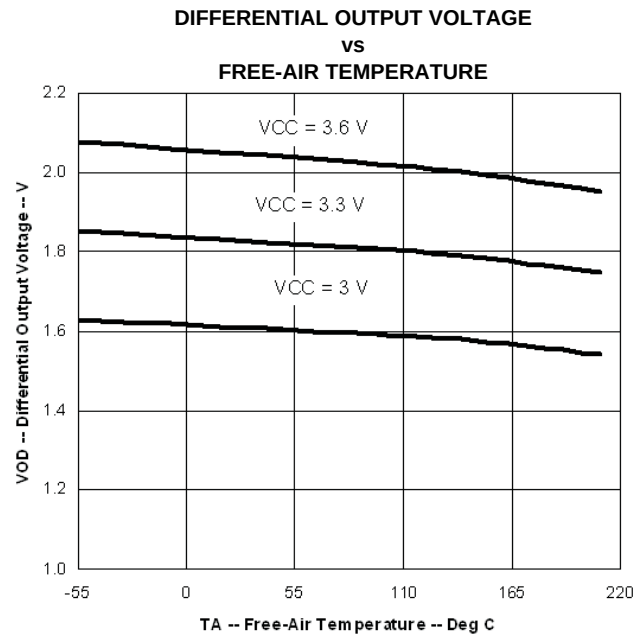
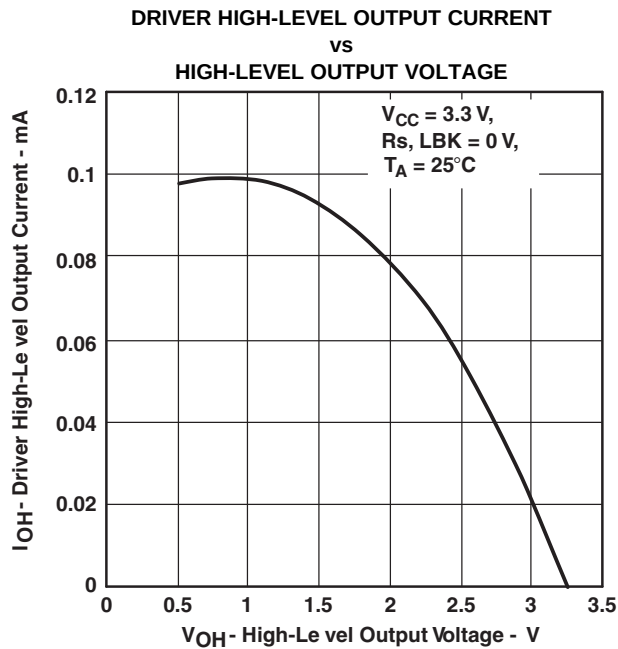


Figure 18.

## TYPICAL CHARACTERISTICS (continued)



## TYPICAL CHARACTERISTICS (continued)

### DRIVER LOW-TO-HIGH PROPAGATION DELAY

vs

FREE-AIR TEMPERATURE

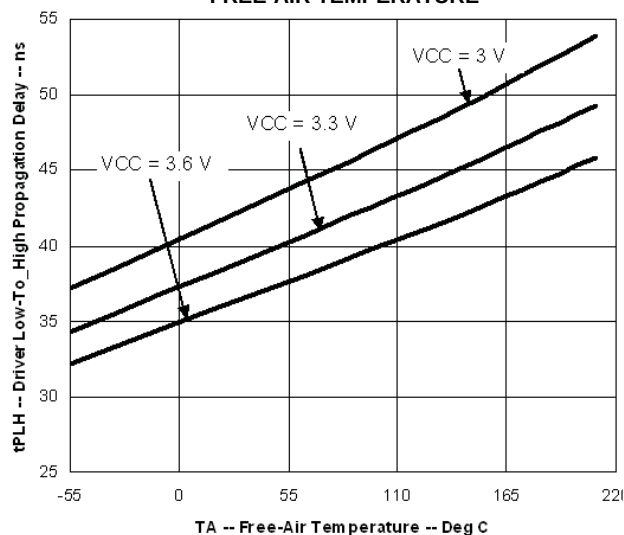


Figure 23.

### DRIVER HIGH-TO-LOW PROPAGATION DELAY

vs

FREE-AIR TEMPERATURE

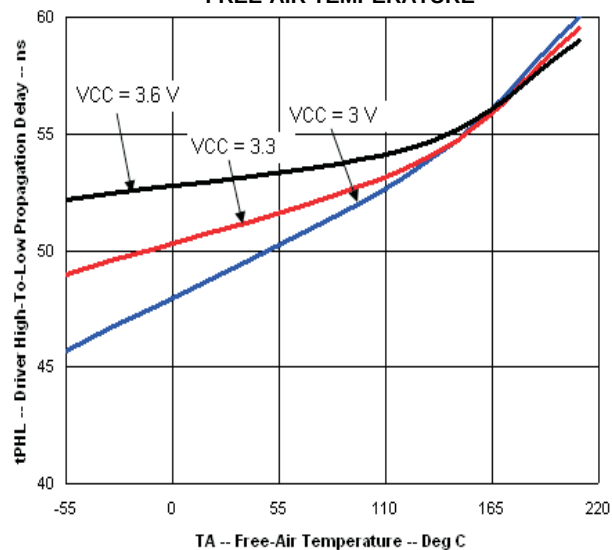


Figure 24.

### DRIVER OUTPUT CURRENT

vs

SUPPLY VOLTAGE

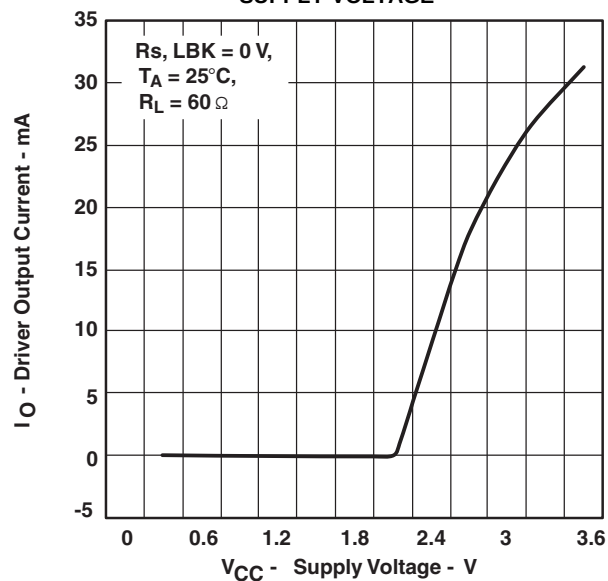


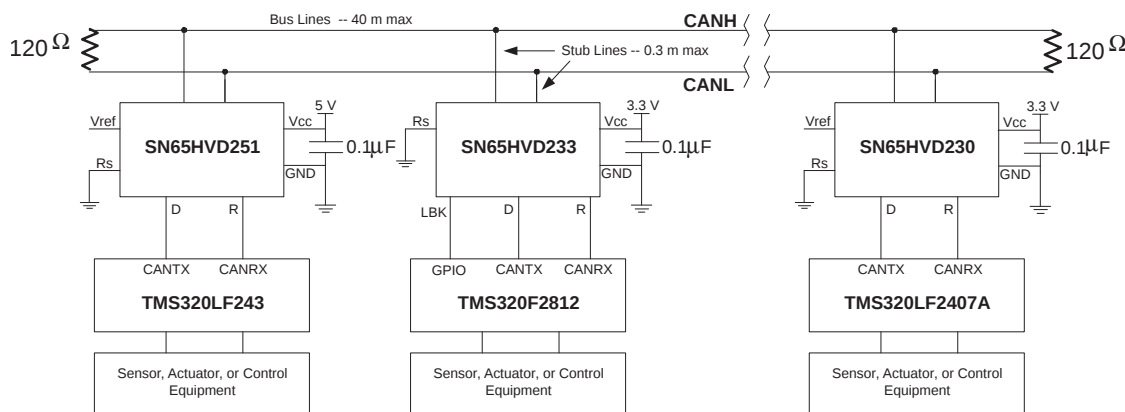
Figure 25.

## APPLICATION INFORMATION

### Diagnostic Loopback

The loopback (LBK) function of the SN65HVD233 is enabled with a high-level input to pin 5. This forces the driver into a recessive state and redirects the data (D) input at pin 1 to the received-data (R) output at pin 4. This allows the host controller to input and read back a bit sequence to perform diagnostic routines without disturbing the CAN bus. A typical CAN bus application is displayed in Figure 26.

If the LBK pin is not used, it may be tied to ground (GND). However, it is pulled low internally (defaults to a low-level input) and may be left open if not in use.



**Figure 26. Typical SN65HVD233 Application**

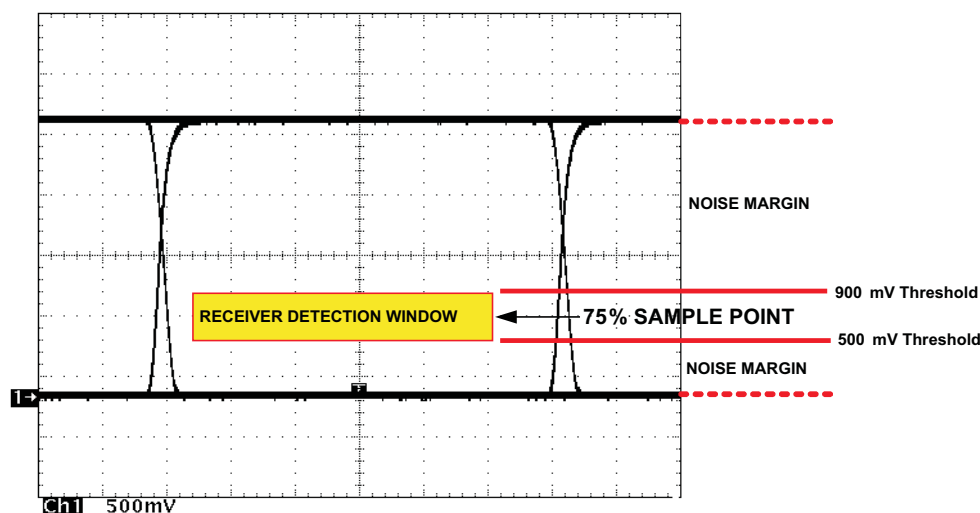
## ISO 11898 Compliance of SN65HVD230 Family of 3.3-V CAN Transceivers

### Introduction

Many users value the low power consumption of operating CAN transceivers from a 3.3-V supply. However, some are concerned about the interoperability with 5-V supplied transceivers on the same bus. This section analyzes this situation to address those concerns.

### Differential Signal

CAN is a differential bus where complementary signals are sent over two wires, and the voltage difference between the two wires defines the logical state of the bus. The differential CAN receiver monitors this voltage difference and outputs the bus state with a single-ended output signal.



**Figure 27. Typical SN65HVD230 Differential Output Voltage Waveform**

The CAN driver creates the difference voltage between CANH and CANL in the dominant state. The dominant differential output of the SN65HVD230 is greater than 1.5 V and less than 3 V across a 60-Ω load. The minimum required by ISO 11898 is 1.5 V and the maximum is 3 V. These are the same limiting values for 5-V supplied CAN transceivers. The bus termination resistors drive the recessive bus state and not the CAN driver.

A CAN receiver is required to output a recessive state with less than 500 mV and a dominant state with more than 900-mV difference voltage on its bus inputs. The CAN receiver must do this with common-mode input voltages from –2 V to 7 V. The SN65HVD230 family receivers meet these same input specifications as 5-V supplied receivers.

### **Common-Mode Signal**

A common-mode signal is an average voltage of the two signal wires that the differential receiver rejects. The common-mode signal comes from the CAN driver, ground noise, and coupled bus noise. Obviously, the supply voltage of the CAN transceiver has nothing to do with noise. The SN65HVD230 family driver lowers the common-mode output in a dominant bit by a couple hundred millivolts from that of most 5-V drivers. While this does not fully comply with ISO 11898, this small variation in the driver common-mode output is rejected by differential receivers and does not affect data, signal noise margins, or error rates.

### **Interoperability of 3.3-V CAN in 5-V CAN Systems**

The 3.3-V-supplied SN65HVD23x family of CAN transceivers are electrically interchangeable with 5-V CAN transceivers. The differential output is the same. The recessive common-mode output is the same. The dominant common-mode output voltage is a couple hundred millivolts lower than 5-V-supplied drivers, while the receivers exhibit identical specifications as 5-V devices.

Electrical interoperability does not assure interchangeability however. Most implementers of CAN buses recognize that ISO 11898 does not sufficiently specify the electrical layer and that strict standard compliance alone does not ensure interchangeability. This comes only with thorough equipment testing.

### **Bus Cable**

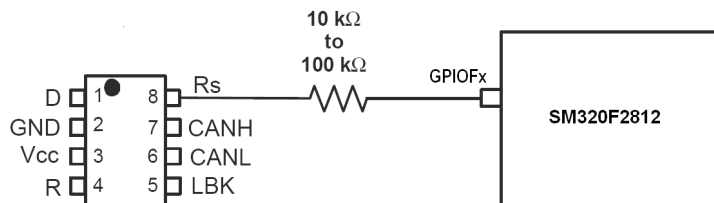
ISO 11898 specifies a maximum bus length of 40 m and maximum stub length of 0.3 m with a maximum of 30 nodes. However, with careful design, users can have longer cables, longer stub lengths, and many more nodes to a bus. A large number of nodes requires a transceiver with high input impedance, such as the SN65HVD233.

The standard specifies the interconnect to be a single twisted-pair cable (shielded or unshielded) with 120- $\Omega$  characteristic impedance ( $Z_0$ ). Resistors equal to the characteristic impedance of the line terminate both ends of the cable to prevent signal reflections. Unterminated drop lines (stubs) connecting nodes to the bus should be kept as short as possible to minimize signal reflections.

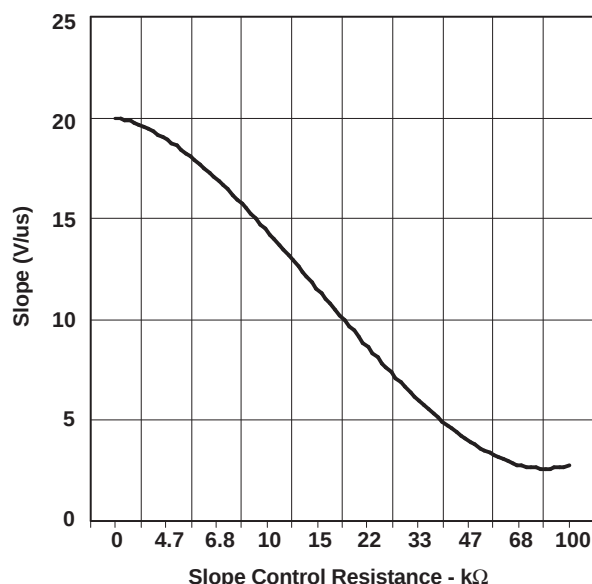
## Slope Control

The rise and fall slope of the SN65HVD233 driver output can be adjusted by connecting a resistor from  $R_s$  (pin 8) to ground (GND), or to a low-level input voltage (see Figure 28).

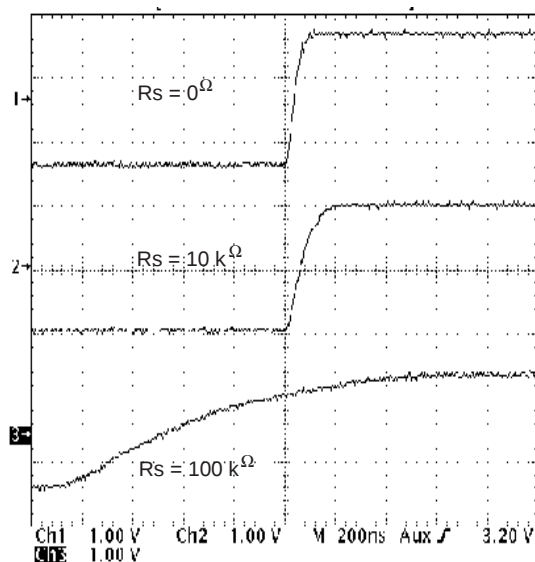
The slope of the driver output signal is proportional to the pin's output current. This slope control is implemented with an external resistor value of 10 k $\Omega$  to achieve a  $\approx 15$ -V/ $\mu$ s slew rate, and up to 100 k $\Omega$  to achieve a  $\approx 2.0$ -V/ $\mu$ s slew rate (see Figure 29). Typical driver output waveforms with slope control are displayed in Figure 30.



**Figure 28. Slope Control/Standby Connection to DSP**



**Figure 29. SN65HVD233 Driver Output Signal Slope vs Slope Control Resistance Value**



**Figure 30. Typical SN65HVD233 250-kbps Output Pulse Waveforms With Slope Control**

## STANDBY

If a high-level input ( $>0.75 V_{CC}$ ) is applied to  $R_s$ , the circuit enters a low-current, *listen-only* standby mode, during which the driver is switched off and the receiver remains active. The local controller can reverse this low-power standby mode when the rising edge of a dominant state (bus differential voltage  $>900$  mV typical) occurs on the bus.

## PACKAGING INFORMATION

| Orderable Device | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2)            | Lead/Ball Finish | MSL Peak Temp<br>(3) | Op Temp (°C) | Top-Side Markings<br>(4) | Samples                 |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| SN65HVD233HD     | ACTIVE        | SOIC         | D                  | 8    | 75             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM   | -55 to 175   | 233S                     | <a href="#">Samples</a> |
| SN65HVD233SHKJ   | ACTIVE        | CFP          | HKJ                | 8    | 1              | TBD                        | Call TI          | N / A for Pkg Type   | -55 to 210   | SN65HVD233S<br>HKJ       | <a href="#">Samples</a> |
| SN65HVD233SHKQ   | ACTIVE        | CFP          | HKQ                | 8    | 25             | TBD                        | AU               | N / A for Pkg Type   | -55 to 210   | HVD233S<br>HKQ           | <a href="#">Samples</a> |
| SN65HVD233SJD    | ACTIVE        | CDIP SB      | JDJ                | 8    | 1              | TBD                        | POST-PLATE       | N / A for Pkg Type   | -55 to 210   | SN65HVD233SJD            | <a href="#">Samples</a> |
| SN65HVD233SKGDA  | ACTIVE        | XCEPT        | KGD                | 0    | 130            | TBD                        | Call TI          | N / A for Pkg Type   | -55 to 210   |                          | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "--" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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**OTHER QUALIFIED VERSIONS OF SN65HVD233-HT :**

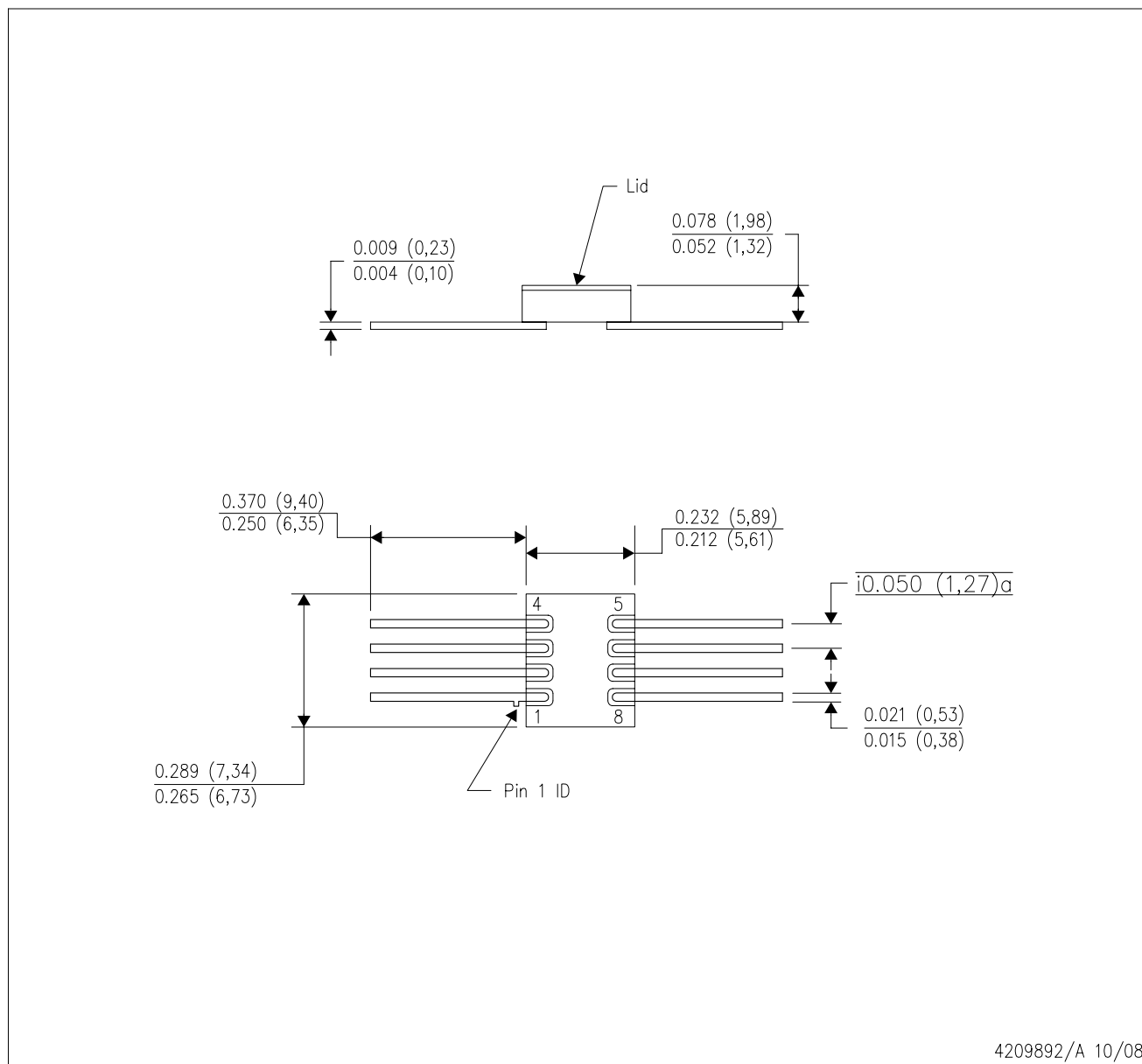
- Catalog: [SN65HVD233](#)
- Enhanced Product: [SN65HVD233-EP](#)

**NOTE:** Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

HKJ (R-CDFP-F8)

CERAMIC DUAL FLATPACK

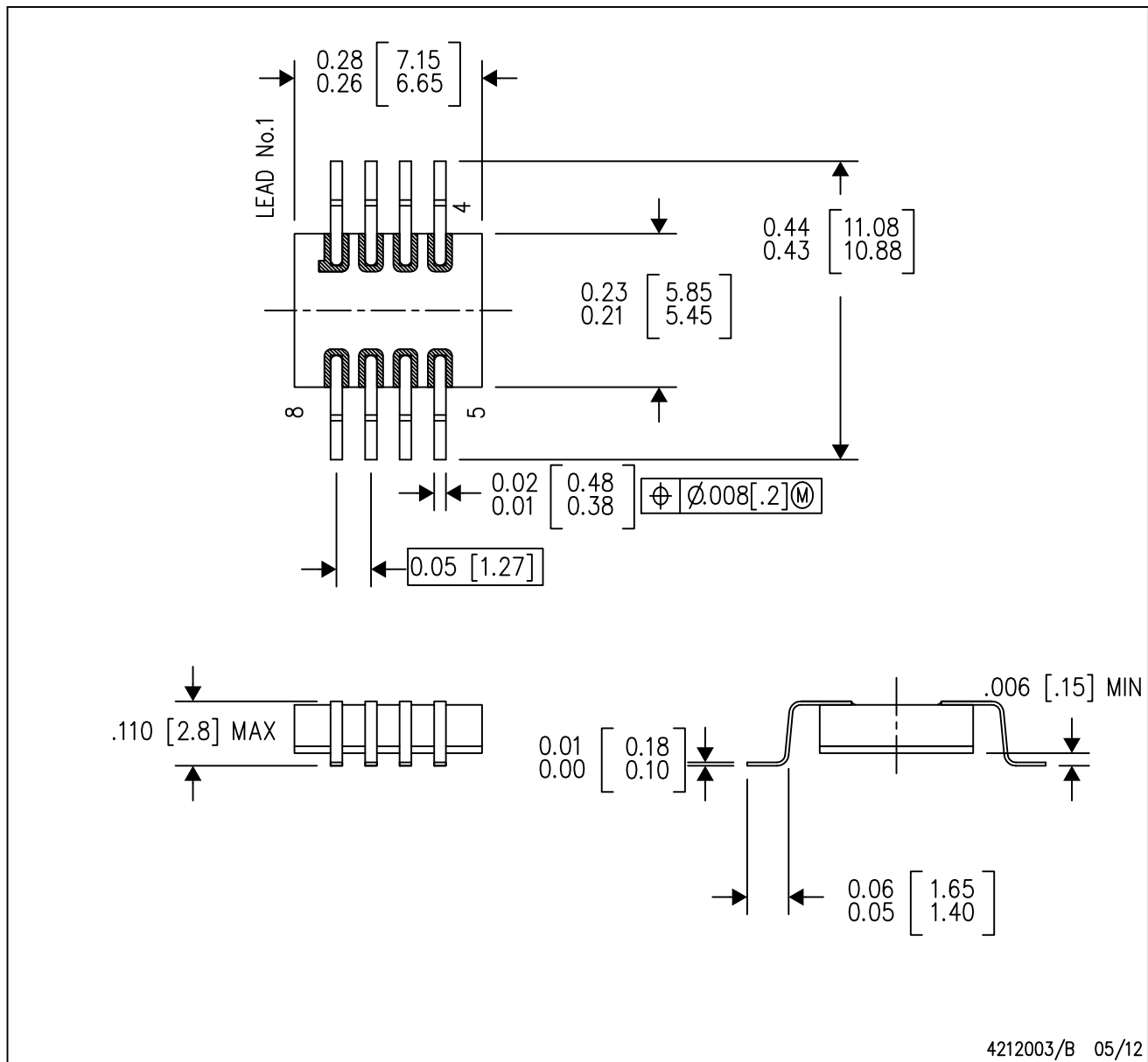


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals will be gold plated.

# MECHANICAL DATA

HKQ (R-CDFP-G8)

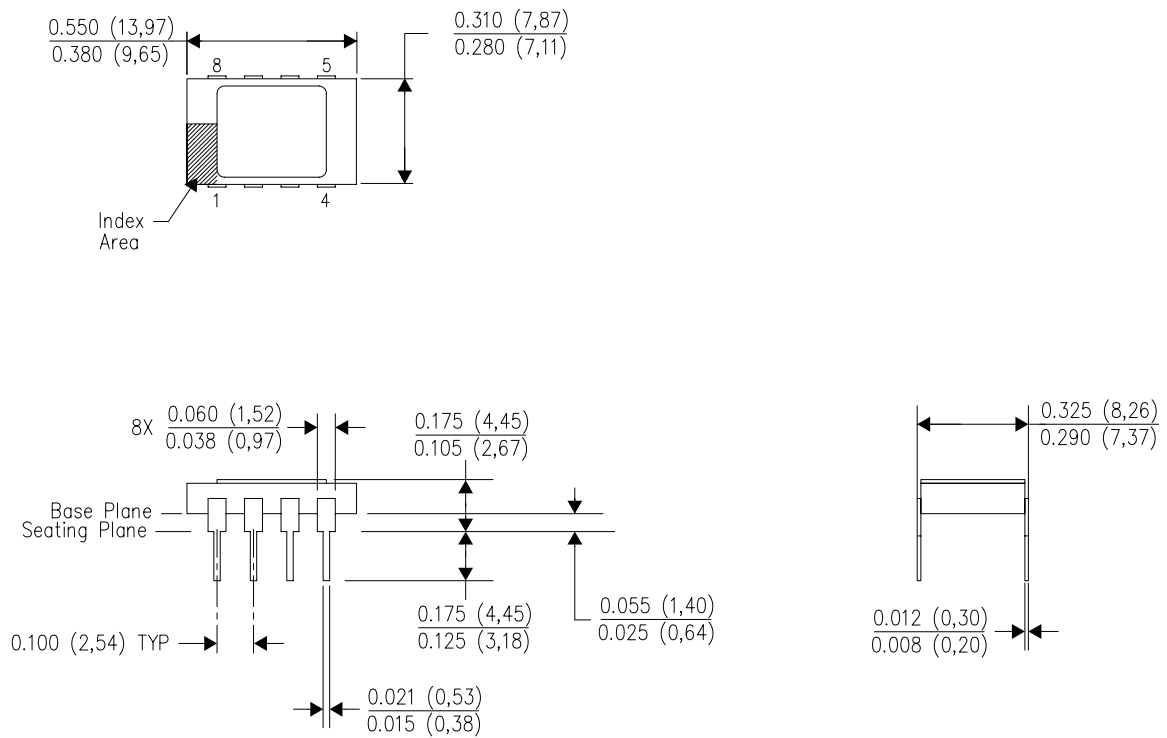
CERAMIC GULL WING



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals will be gold plated.
  - E. Lid is not connected to any lead.

JDJ (R-CDIP-T8)

CERAMIC DUAL IN-LINE PACKAGE



4202646-2/B 07/10

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Ceramic quad flatpack with flat leads brazed to non-conductive tie bar carrier.
  - D. This package is hermetically sealed with a metal lid.
  - E. The leads are gold plated and can be solderdipped.
  - F. Leads not shown for clarity purposes.
  - G. Lid and heat sink are connected to GND leads.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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